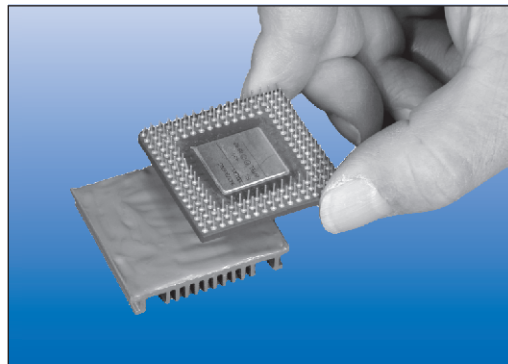


# DURALCO 132

## 500°F Thermally Conductive Adhesive

- *Just Mix and Apply*
- *Cures at Room Temperature*
- *Provides Fast Heat Transfer*
- *Ideal for any Industrial, Electrical or Electronic Application*



**Duralco 132 Dissipates Heat in  
A Semi Conductor Device**

### Duralco™ 132 500°F Adhesive

Combines Cotronics' unique, high temperature resins with highly conductive fillers to form thermally conductive, adhesive bonds with continuous service up to 500°F.

Easy to use.

Just mix and apply.

Duralco 132 has excellent adhesion to metals, glass, ceramics, and plastics.

Offers excellent resistance to chemicals solvents and moisture.

Provides the heat dissipation required for many high temperature electronic and industrial applications.

#### Users Report:

- Duralco 132 dissipates heat in a semiconductor device.
- Duralco 132 transfers the heat generated in high power devices and provides for efficient cooling.
- Duralco 132 bonds electrical heating elements for fluid heating.

**Applications include:** bonding and assembling heating coils, cooling coils, heating elements, heat sinks, reaction vessels, semi-conductors, rectifiers, power supplies, etc.

Duralco 132 is commonly used as a heat tracing adhesive and as a replacement for soldering and welding.

Duralco 132 is the ideal choice for high power, high temperature, electronic or industrial applications requiring high thermal conductivity.

#### Availability:

Cat No.	Description	Temp.
Duralco 132-1 . . . . .	16 oz. Kit . . . . .	500 °F
Duralco 132-2 . . . . .	32 oz. Kit . . . . .	500 °F
Duralco 132P . . . . .	8 oz putty . . . . .	500 °F

#### Pre-Measured Kits

EE 132-10 . . . . .	10 Epox-Eez™	10 gm Units/Box
EE 132-25 . . . . .	10 Epox-Eez™	25 gm Units/Box

**Each Unit Contains:** 1 jar of resin, 1 syringe of hardener and 1 mixing stick. (See page 53 for details.)



**Duralco 132 Bonds Electrical  
Heating Element for Fluid Heating**

### Physical Properties

Maximum Temp	°F	500
Components -Color		2
Components -Color		Silver
Viscosity	cps	36,500 cps
Cure	Hr. @ R.T.	16-24
	Mins.@ 250°F	5
Hardness	Shore 'D'	85
Flexural Strength	psi	1,150
Compressive Strength	psi	6,000
Thermal Conductivity*	BTU- in Units	40
Thermal Expansion	10 <sup>-5</sup> / °C	4.1
Volume Resistivity	ohm-cm	10 <sup>6</sup>
Heat Distortion	°C	210
Thermal Stability	%1000 hr @ 200°C	0.2
Shrinkage	% max.	0.8
Moisture Absorption	30 Days %	0.2
Mix Ratio	R / H	100 / 27.3

\* Thermal Conductivity Units = Btu-in/ Hr. Ft<sup>2</sup> °F



**COTRONICS** CORPORATION

Quantity Prices and Custom Formulations,  
Available on request